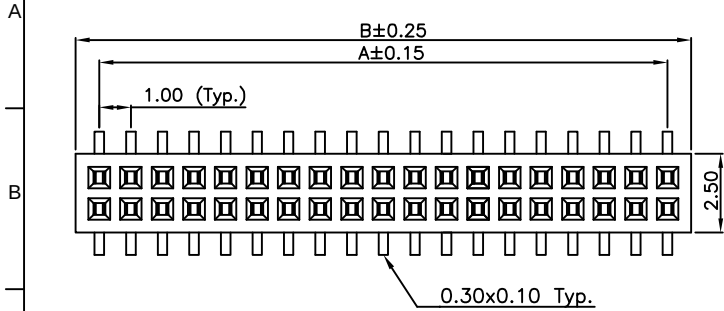
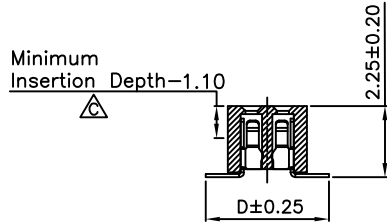
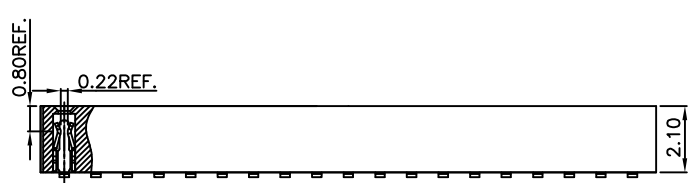
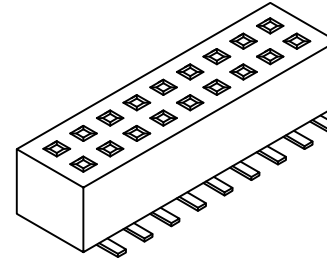


RECOMMENDED PCB LAYOUT
(Tolerance:±0.05)



Ordering Grid

BC085-XX-X-XXXX-L-X

REQUEST SAMPLES AND QUOTATION

SPECIFICATIONS 规格:

CURRENT RATING 电流额定值: 0.5 AMP
INSULATOR RESISTANCE 绝缘电阻值: 500 MEGOHMS MIN.
DIELECTRIC WITHSTANDING 耐电压: AC 200 V
CONTACT RESISTANCE 接触电阻值: 40mΩ Max.
OPERATING TEMPERATURE 工作温度: -40°C TO +105°C
CONTACT MATERIAL 端子物料: PHOSPHOR BRONZE
INSULATOR MATERIAL 绝缘体物料:
STANDARD 标准物料: POLYESTER 聚酯, LCP, UL 94-V0
SOLDERING PROCESS 可焊性:
LCP (STANDARD 标准物料) -
IR REFLOW 回流焊: 260°C for 10 sec.
WAVE 波峰焊: 250°C for 5-10 sec
MANUAL SOLDER 人工焊接: 350°C for 3-5 sec

No. of Contacts
04 to 80
Contact Plating
A = Gold Flash All Over
C = Tin All Over
Standard = Gold Flash All Over

Packing Options
C = Tape and Reel with Film (Standard)
B = Tape and Reel with Cap
D = Tube
E = Tube with Cap
F = Tube with Film
Insulator Material
L = LCP (Standard)

Dimension D (1/100mm)
(Footprint Width)
Standard - 3.90mm = 0390
or specify Dimension D
e.g. 2.50mm = 0250
Tol ± 0.2mm

MATES WITH 配套之母座 (SUBJECT TO PIN LENGTH 在端子长度适合的条件下)

BC035 BC036 BC040 BC045 BC050
BC055 BC057

By	ASE	GG	PN	SA	SA
DETAIL	DRAWING RELEASE	CHANGE TO SOLDER TEMP. INFORMATION	MINIMUM INSERTION DEPTH ADDED	PEG OPTION REMOVED, SPECIFICATION UPDATED	AMENDMENT TO PLATING OPTIONS
REV DATE	A 20/05/08	B 23/07/09	C 30/11/09	D 01/12/09	E 21/12/09



Tolerances (Except as noted)		Part Number:-	Date:-	GCT www.globalconnectortechology.com					
Dimensions in mm		BC085	20 MAY 08						
Description:-		1.0mm PITCH SOCKET, DUAL ROW, SURFACE MOUNT, VERTICAL							
X. ± 0.30 X."± 5"									
X.X ± 0.25 X."± 3"				Scale NTS	Revision E	Material See Note	Drawn by ASE	E & OE	Sheet No. 1/1
X.XX ± 0.15 X.X"± 2"									
X.XXX ± 0.10 X.XX"± 1"									
 Third Angle Projection		 THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT							